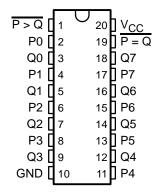
SCLS340B - MARCH 1996 - REVISED MARCH 2003

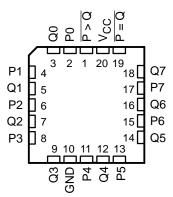
- Wide Operating Voltage Range of 2 V to 6 V
- High-Current Outputs Drive Up To 10 LSTTL Loads
- Low Power Consumption, 80-μA Max I_{CC}

SN54HC684 . . . J OR W PACKAGE SN74HC684 . . . DW OR N PACKAGE (TOP VIEW)



- Typical t_{pd} = 22 ns
- ±4-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- Compare Two 8-Bit Words

SN54HC684 . . . FK PACKAGE (TOP VIEW)



description/ordering information

These magnitude comparators perform comparisons of two 8-bit binary or BCD words. These devices provide $\overline{P} = \overline{Q}$ and $\overline{P} > \overline{Q}$ outputs.

ORDERING INFORMATION

TA	PACK	AGE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING		
	PDIP – N	Tube	SN74HC684N	SN74HC684N		
–40°C to 85°C	SOIC - DW	Tube	SN74HC684DW	HC684		
	201C – DW	Tape and reel	SN74HC684DWR	ПС004		
	CDIP – J	Tube	SNJ54HC684J	SNJ54HC684J		
–55°C to 125°C	CFP – W Tube		SNJ54HC684W	SNJ54HC684W		
	LCCC – FK	Tube	SNJ54HC684FK	SNJ54HC684FK		

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

DATA	OUTPUTS						
INPUTS P, Q	P = Q	P > Q					
P = Q	L	Н					
P > Q	Н	L					
P < Q	Н	Н					

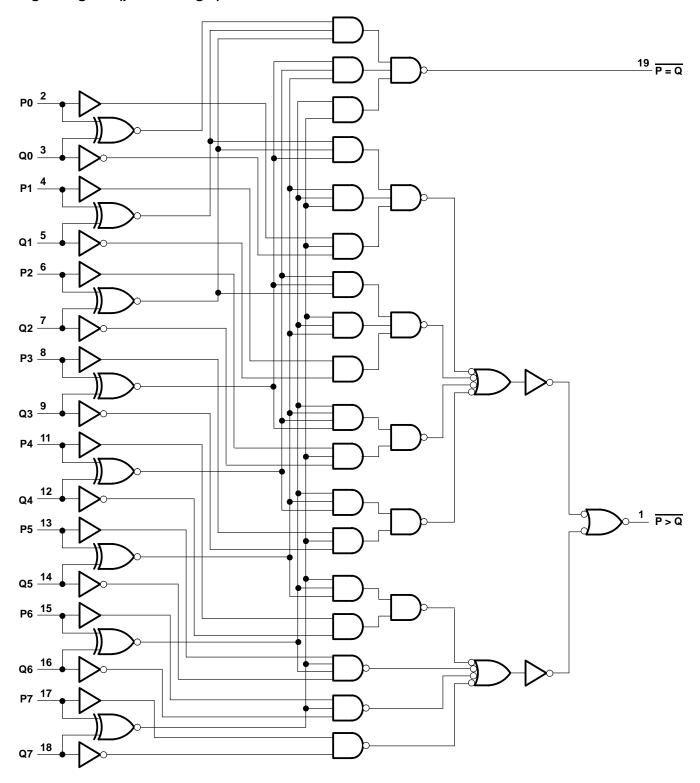
The \overline{P} < \overline{Q} function can be generated by applying \overline{P} = \overline{Q} and \overline{P} > \overline{Q} to a 2-input NAND gate.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



logic diagram (positive logic)





SCLS340B - MARCH 1996 - REVISED MARCH 2003

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I (see Note 1)	0.5 V to 7 V
Output voltage range, VO (see Note 1)	0.5 V to V _{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC})	±20 mA
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$	±25 mA
Continuous current through V _{CC} or GND	±50 mA
Package thermal impedance, θ_{JA} (see Note 2): DW package	58°C/W
N package	69°C/W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

			SN	SN54HC684		SN	UNIT			
			MIN	NOM	MAX	MIN	NOM	MAX	UNII	
Vcc	Supply voltage		2	5	6	2	5	6	V	
		V _{CC} = 2 V	1.5			1.5				
ViH	High-level input voltage	V _{CC} = 4.5 V	3.15			3.15			V	
		V _{CC} = 6 V	4.2		ih	4.2				
		V _{CC} = 2 V		0.5				0.5		
VIL	Low-level input voltage	$V_{CC} = 4.5 \text{ V}$		1.35				1.35	V	
		V _{CC} = 6 V		1.8				1.8		
٧I	Input voltage		0	5	VCC	0		VCC	V	
٧o	Output voltage		0		VCC	0		VCC	V	
		V _{CC} = 2 V	Q		1000			1000		
t _t	Input transition (rise and fall) times	V _{CC} = 4.5 V			500			500	ns	
		V _{CC} = 6 V			400			400		
TA	Operating free-air temperature		-55		125	-40		85	°C	

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

SCLS340B - MARCH 1996 - REVISED MARCH 2003

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST C	ONDITIONS	Vaa	Т	A = 25°C	;	SN54H	C684	SN74HC684		UNIT	
PARAMETER	1251 CC	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT		
			2 V	1.9	1.998		1.9		1.9			
		$I_{OH} = -20 \mu A$	4.5 V	4.4	4.499		4.4		4.4			
VOH	VI = VIH or VIL		6 V	5.9	5.999		5.9		5.9		V	
		$I_{OH} = -4 \text{ mA}$	4.5 V	3.98	4.30		3.7	N.	3.84			
		$I_{OH} = -5.2 \text{ mA}$	6 V	5.48	5.80		5.2	N.	5.34			
	V _I = V _{IH} or V _{IL}		2 V		0.002	0.1		0.1		0.1		
		$I_{OL} = 20 \mu A$	4.5 V		0.001	0.1	43	0.1		0.1		
VOL			6 V		0.001	0.1	n _G	0.1		0.1	V	
		$I_{OL} = 4 \text{ mA}$	4.5 V		0.17	0.26	0.4			0.33		
		$I_{OL} = 5.2 \text{ mA}$	6 V		0.15	0.26	Q'	0.4		0.33		
l _{IH}	$V_I = V_{CC}$		6 V		0.1	100		1000		1000	nA	
Ι _{ΙL}	V _I = 0		6 V		-0.1	-100		-1000		-1000	nA	
ICC	$V_I = V_{CC}$ or 0,	IO = 0	6 V			8		160		80	μΑ	
Ci			2 V to 6 V		3	10		10		10	pF	

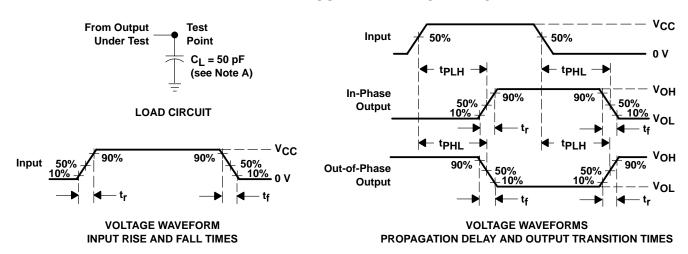
switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	Vaa	T	λ = 25°C	;	SN54H	C684	SN74H	C684	UNIT
TANAMETER ((INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
^t pd		Any	2 V		130	275		413		344	
	P or Q		4.5 V		26	55		88		69	ns
			6 V		22	47		70		58	
		Any	2 V		38	75	35	110		95	
t _t			4.5 V		8	15	90	22		19	ns
			6 V		6	13	PA	19		16	

operating characteristics, T_A = 25°C

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance	No load	40	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \ \Omega$, $t_f = 6 \ ns$, $t_f = 6 \ ns$.
- C. The outputs are measured one at a time with one input transition per measurement.
- D. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms

www.ti.com 14-Oct-2022

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74HC684DW	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC684	Samples
SN74HC684N	ACTIVE	PDIP	N	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC684N	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.



PACKAGE OPTION ADDENDUM

www.ti.com 14-Oct-2022

PACKAGE MATERIALS INFORMATION

www.ti.com 9-Aug-2022

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74HC684DW	DW	SOIC	20	25	507	12.83	5080	6.6
SN74HC684N	N	PDIP	20	20	506	13.97	11230	4.32

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOIC



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2022, Texas Instruments Incorporated